

XSmart e-Passport V1.2

LG CNS

Certificate Effectiveness Maintenance Report

Certification No : KECS-ISIS-0319-2011

July 2011



IT Security Certification Center

1. TOE

XSmart e-Passport V1.2

2. Date of Application

24 June 2011

3. Date of Activity

8 July 2011

4. Overview

The change is that IC Chip (Samsung S3CT9KC) as a platform of the TOE is simply added. S3CT9KC and S3CT9KW are almost the same except EEPROM size. The change to the certified product has no effect on assurance.

Therefore, the assurance as outlined in the Certification Report KECS-ISIS-0319-2011 is maintained for this version of the product.

This report is an addendum to Certification Report KECS-ISIS-0319-2011.

5. Changes to TOE

The IC Chip (Samsung S3CT9KC) as a platform of the TOE is added, but the security relevant implementations (source code) for the TOE are not changed. The reason is that S3CT9KC and S3CT9KW are almost the same except EEPROM size. The difference between S3CT9KW and S3CT9KC is described in the following table.

	S3CT9KW	S3CT9KC
CR No.	BSI-DSZ-CC-0639-2010	BSI-DSZ-CC-0639-2010-MA-01 ※ Maintenance version of S3CT9KW
EAL	EAL5+(AVA_VAN.5, ALC_DVS.2)	EAL5+(AVA_VAN.5, ALC_DVS.2)
H/W	16bit SecuCalm16 CPU	16bit SecuCalm16 CPU

	6KB RAM	6KB RAM
	2.5KB Crypto RAM	2.5KB Crypto RAM
	384KB ROM	384KB ROM
	144KB EEPROM	80KB EEPROM
	DES Accelerator	DES Accelerator
	AES Accelerator	AES Accelerator
	RSA/ECC Accelerator "TORNADO	RSA/ECC Accelerator "TORNADO
	2Mx2"	2Mx2"
	16-bits True Random Number	16-bits True Random Number
	Generator	Generator
	Abnormal condition detectors	Abnormal condition detectors
	Memory protection unit	Memory protection unit
	2 16-bit timer	2 16-bit timer
	20-bit watchdog timer	20-bit watchdog timer
	ISO7816/14443 compliant	ISO7816/14443 compliant
s/w	Secure RSA/ECC library v1.0	Secure RSA/ECC library v1.0
	TRNG library v1.0	TRNG library v1.0
	DRNG library v1.0	DRNG library v1.0

6. Assessment

The vendor for XSmart e-Passport V1.2 submitted IAR [2] to IT Security Certification Center for approval. The IAR is intended to satisfy the requirements outlined in the document Assurance Continuity [1]. The IAR includes the following items;

- A. The changes made to the certified TOE
- B. The evidence updated as a result of the changes and,

C. The security impact of the changes

The vendor added S3CT9KC as H/W platform of XSmart e-Passport V1.2.

S3CT9KW was certified by BSI (BSI-DSZ-CC-0639-2010) and the assurance for S3CT9KC was maintained by BSI (BSI-DSZ-CC-0639-2010-MA-01). The TOE with S3CT9KC is correctly operated and meets all the SFRs in its security target [3].

7. Conclusion

The change to the TOE is that the IC Chip (Samsung S3CT9KC) as a platform of the TOE is added. There were editorially updated in some evidences due to add H/W platform (S3CT9KC). Examination of the evidence indicates that the change performed is limited to the following documents.

- XSmart e-Passport V1.2 ASE V1.6
- XSmart e-Passport V1.2 FSP V1.7
- XSmart e-Passport V1.2 ARC V1.4
- XSmart e-Passport V1.2 IMP V1.6
- XSmart e-Passport V1.2 INT V1.4
- XSmart e-Passport V1.2 TDS V1.2
- XSmart e-Passport V1.2 ACM V1.5
- XSmart e-Passport V1.2 AGD V1.4
- XSmart e-Passport V1.2 DEL V1.2

Consideration of the nature of the change leads to the conclusion that it is classified as a minor change and that certificate maintenance is the correct path to continuity of assurance.

Therefore, IT Security Certification Center agrees that the assurance as outlined in the Certification Report [4] is maintained for this version of the product.

8. References

- [1] Common Criteria document CCIMB-2004-02-2009 “Assurance Continuity: CCRA Requirements”, version 1.0, February 2004
- [2] Security Impact Analysis Report, “XSmart e-Passport V1.2 Security Impact Analysis Report”, version 1.0, June 2011
- [3] Security Target Lite of XSmart e-Passport V1.2, version 1.0, May 2011
- [4] Certification Report, “XSmart e-Passport V1.2 CR(KECS-ISIS-0319-2011)”, June 2011